

Title (en)  
SURFACE MICROSTRUCTURING DEVICE

Title (de)  
VORRICHTUNG ZUR OBERFLÄCHENMIKROSTRUKTIERUNG

Title (fr)  
DISPOSITIF DE MICROSTRUCTURATION DE SURFACE

Publication  
**EP 1779200 A1 20070502 (FR)**

Application  
**EP 05783993 A 20050701**

Priority  
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Abstract (en)  
[origin: WO2006013257A1] The invention concerns a device for microstructuring the surface of at least one substrate characterized in that it comprises a support frame (2) including at least means (6) for conveying the substrate (S) comprising preferably means (15) for supporting the substrate adapted to maintain the substrate in or relative to each of the modules so as to avoid any change of support when the substrate is shifted from one module to the other, a module for applying a photosensitive resin layer on the substrate, a module (20) for automatic exposure using a laser beam of the resin layer on the substrate based on a programmed scheme, a so-called developing module for removing the part of the resin layer which has been exposed of the part or the resin layer which has not been exposed, a module for chemically etching the substrate, a module for cleaning the substrate, and a control unit (7).

IPC 8 full level  
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